

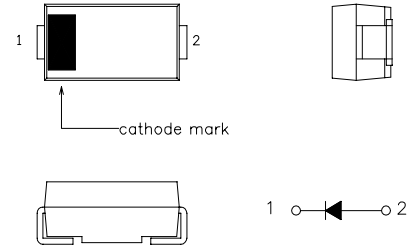
DIODE Type : EC10DA40

Electrostatic Discharge Reinforcement Type

FEATURES

- * Miniature Size, Surface Mount Device
- * High Surge Capability
- * Low Forward Voltage Drop
- * Low Reverse Leakage Current
- * Packaged in 12mm Tape and Reel

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC10DA40		Unit
Repetitive Peak Reverse Voltage	V_{RRM}	400		V
Non-repetitive Peak Reverse Voltage	V_{RSM}	450		V
Average Rectified Output Current	I_O	0.76	$T_a=25\text{ }^\circ\text{C}$ *1	50Hz Half Sine Wave Resistive Load
		1.0	$T_a=29\text{ }^\circ\text{C}$ *2	
RMS Forward Current	$I_{F(RMS)}$	1.57		A
Surge Forward Current	I_{FSM}	25	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	T_{jw}	-40 to +150		$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40 to +150		$^\circ\text{C}$

Electrical • Thermal Characteristics

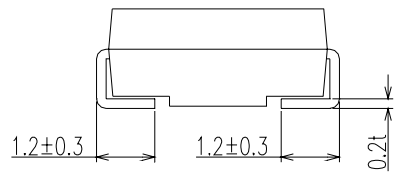
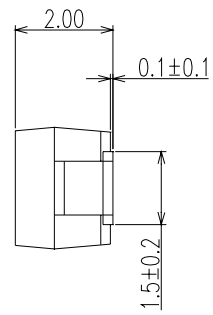
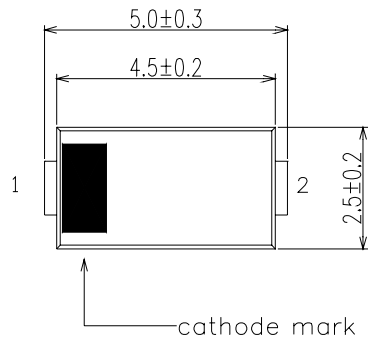
Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	I_{RM}	$T_j= 25^\circ\text{C}$, $V_{RM}= V_{RRM}$	-	-	10	μA	
Peak Forward Voltage	V_{FM}	$T_j= 25^\circ\text{C}$, $I_{FM}= 1.0\text{A}$	-	-	1.05	V	
Electrostatic Discharge	-	$T_j= 25^\circ\text{C}$, $C = 150\text{ pF}$, $R = 150\text{ ohm}$ *3	-	25	-	kV	
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	-	157	$^\circ\text{C}/\text{W}$
			*2	-	-	108	

*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*3 Measured by ESS-630S of NOISE LABORATORY

EC10DA40 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

